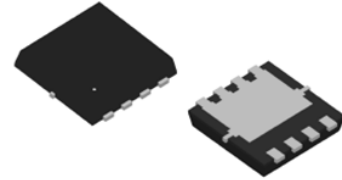


## WPM3035

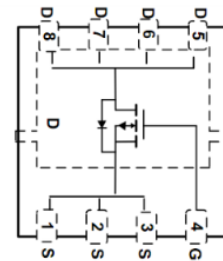
### Single P-Channel,-30V,-23A,Power MOSFET

[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

V <sub>DS</sub> (V)	Typical R <sub>DS(on)</sub> (mΩ)
-30	16.5 @ V <sub>GS</sub> =-10V
	24.0 @ V <sub>GS</sub> =-4.5V



PDFN3333-8L



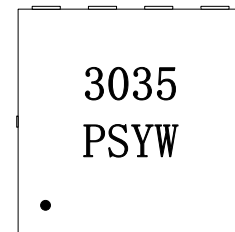
Pin configuration (Top view)

### Descriptions

The WPM3035 is P-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WPM3035 is Pb-free.

### Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package PDFN3333-8L



3035 = Device Code  
 PS =Special Code  
 Y = Year  
 W = Week(A~z)

### Marking

### Applications

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

### Order information

Device	Package	Shipping
WPM3035-8/TR	PDFN3333-8L	2500/Tape&Reel

**Absolute Maximum ratings**

Parameter	Symbol	Maximum	Unit	
Drain-Source Voltage	$V_{DS}$	30	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current <sup>d</sup>	$I_D$	$T_C=25^\circ\text{C}$	-23	A
		$T_C=100^\circ\text{C}$	-14	A
Pulsed Drain Current <sup>c</sup>	$I_{DM}$	-80	A	
Continuous Drain Current	$I_{DSM}$	$T_A=25^\circ\text{C}$	-11	A
		$T_A=70^\circ\text{C}$	-9	
Avalanche Energy $L=0.3\text{mH}$	$E_{AS}$	43	mJ	
Power Dissipation <sup>b</sup>	$P_D$	$T_C=25^\circ\text{C}$	15	W
		$T_C=100^\circ\text{C}$	6	
Power Dissipation <sup>a</sup>	$P_{DSM}$	$T_A=25^\circ\text{C}$	3.7	W
		$T_A=70^\circ\text{C}$	2.4	
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ\text{C}$	
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ\text{C}$	

**Thermal resistance ratings**

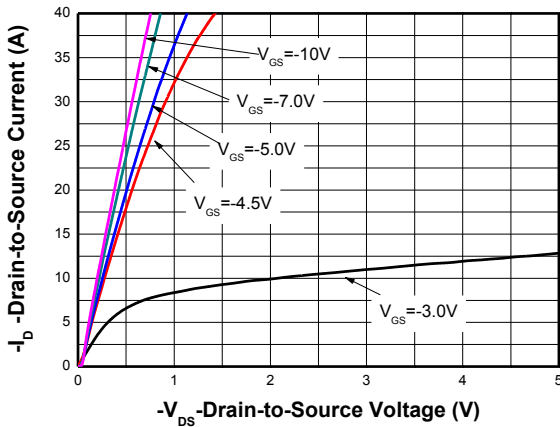
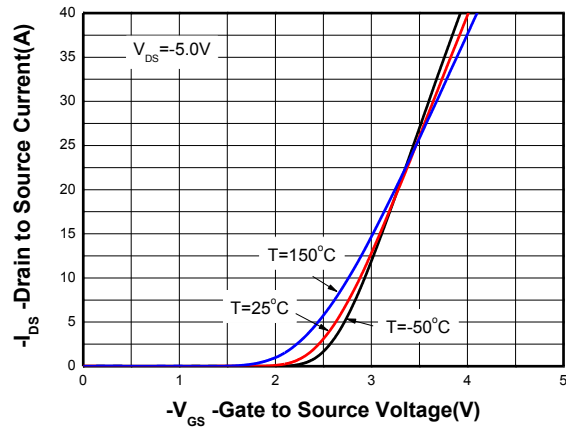
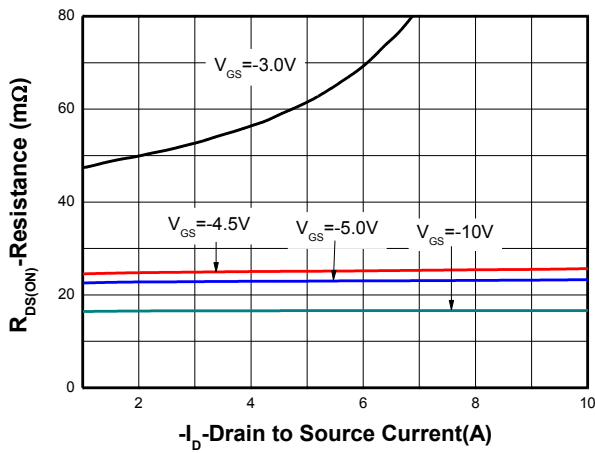
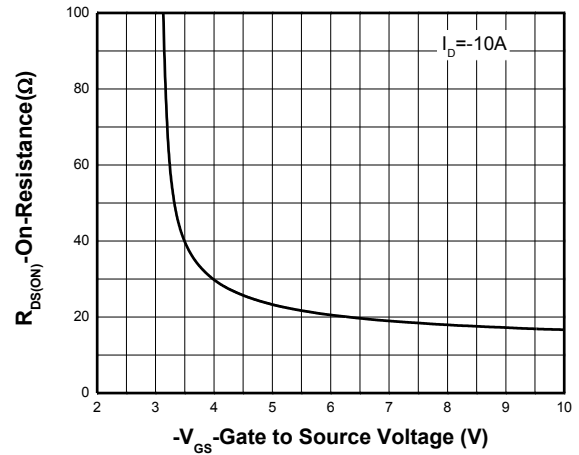
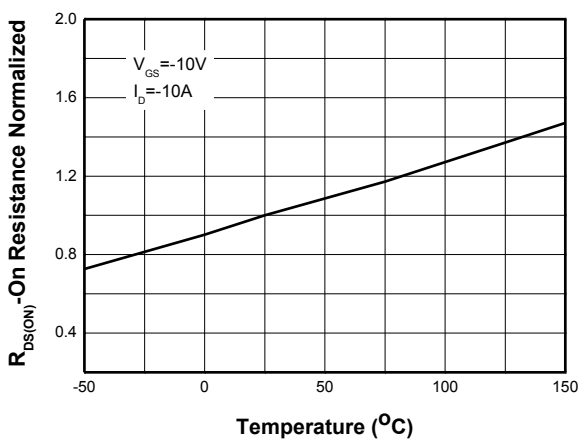
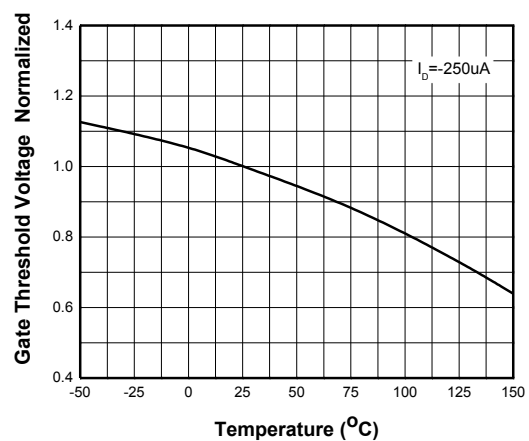
Single Operation					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$R_{\theta JA}$	$t \leq 10\text{ s}$	27	34	$^\circ\text{C/W}$
		Steady State	54	67	
Junction-to-Case Thermal Resistance	$R_{\theta JC}$	6.5	8.1		

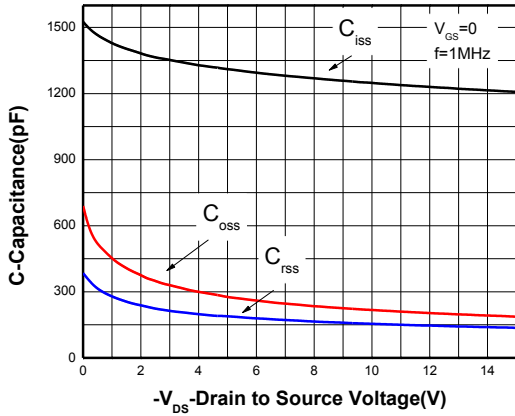
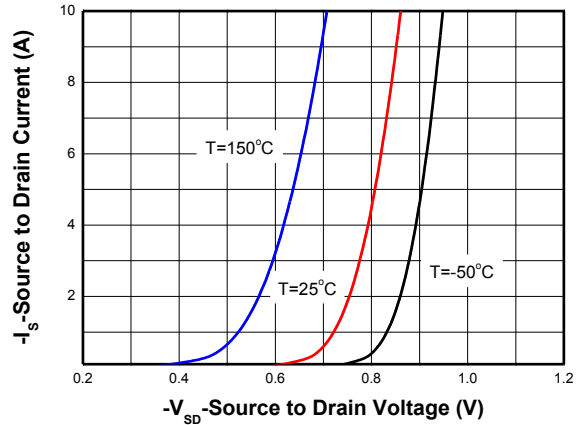
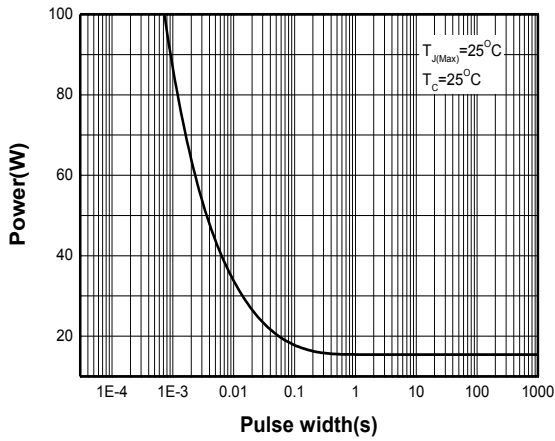
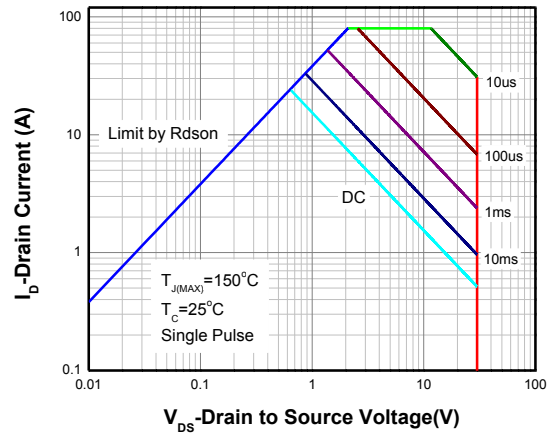
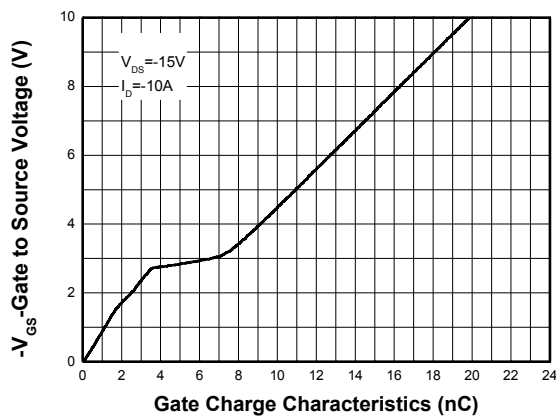
**Note:**

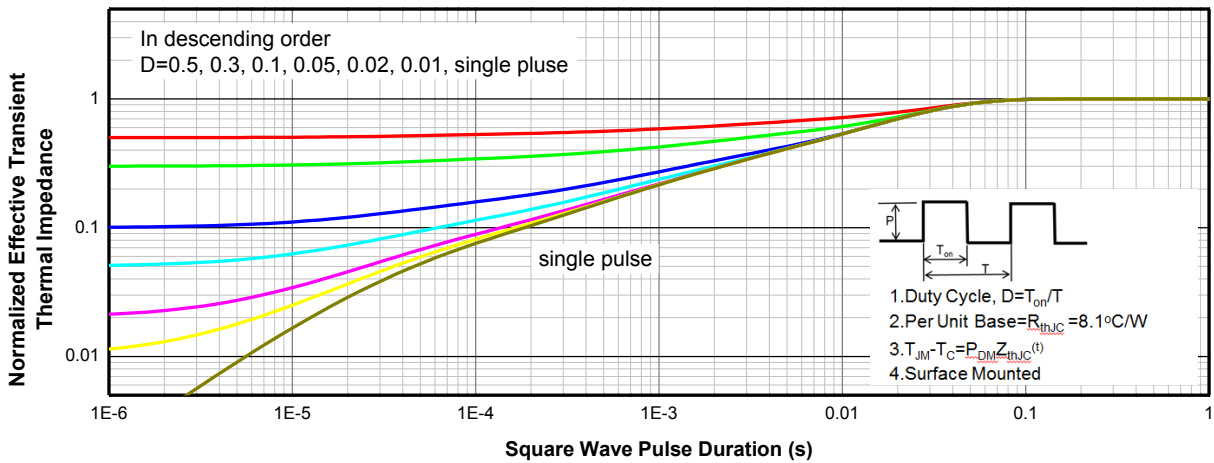
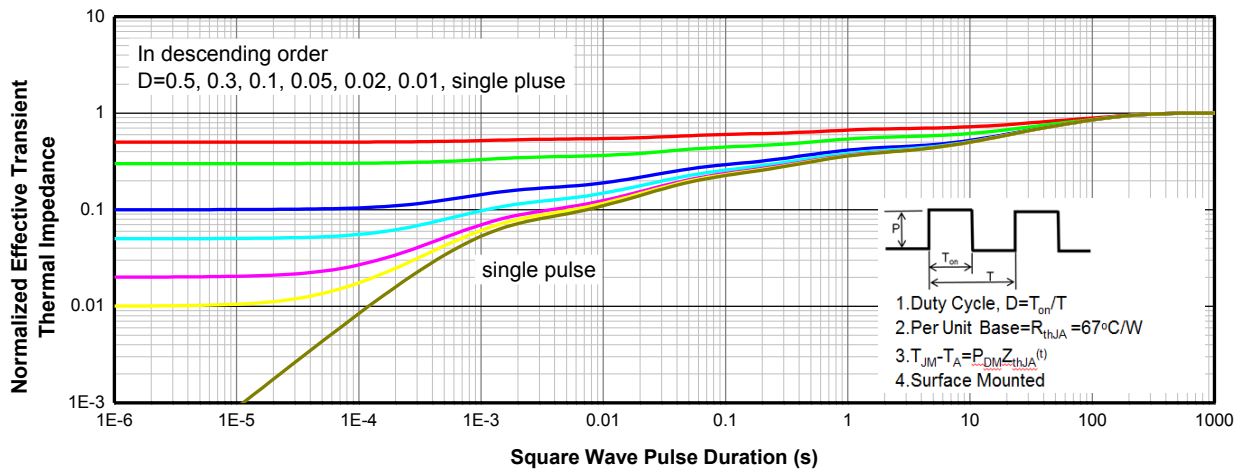
- a The value of  $R_{\theta JA}$  is measured with the device mounted on 1-inch<sup>2</sup> (6.45cm<sup>2</sup>) with 2oz.(0.071mm thick) Copper pad on a 1.5\*1.5 inch<sup>2</sup>, 0.06-inch thick FR4 PCB, in a still air environment with  $T_A = 25^\circ\text{C}$ . The power dissipation  $P_{DSM}$  is based on  $R_{\theta JA} t \leq 10\text{s}$  value and the  $T_{J(MAX)}=150^\circ\text{C}$ . The value in any given application is determined by the user's specific board design.
- b The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- c Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial  $T_J = 25^\circ\text{C}$ , the maximum allowed junction temperature of 150 $^\circ\text{C}$ .
- d The maximum current rating by source bonding technology.
- e The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

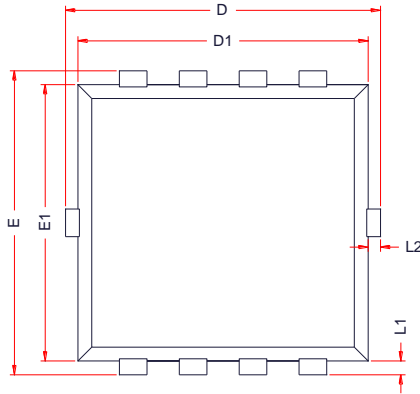
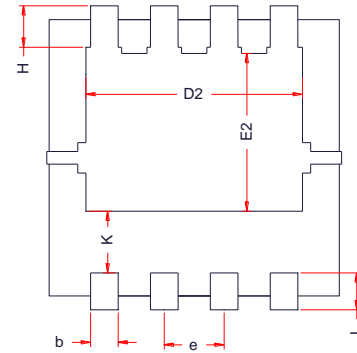
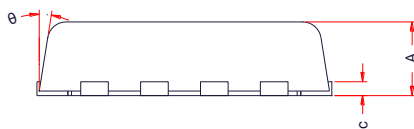
**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = -250\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -24\text{ V}, V_{GS} = 0\text{ V}$			-1	$\mu\text{A}$
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-1.3	-1.6	-2.4	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = -10\text{ V}, I_D = -10\text{ A}$		16.5	20	m $\Omega$
		$V_{GS} = -4.5\text{ V}, I_D = -8\text{ A}$		24.0	32	
Forward Transconductance	$g_{FS}$	$V_{DS} = -15\text{ V}, I_D = -10\text{ A}$		6		S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, F = 1.0\text{ MHz},$ $V_{DS} = -15\text{ V}$		1200		pF
Output Capacitance	$C_{OSS}$			180		
Reverse Transfer Capacitance	$C_{RSS}$			130		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -10\text{ V}, V_{DS} = -24\text{ V},$ $I_D = -10\text{ A}$		20		nC
Threshold Gate Charge	$Q_{G(TH)}$			1.7		
Gate-to-Source Charge	$Q_{GS}$			3.4		
Gate-to-Drain Charge	$Q_{GD}$			3.6		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -10\text{ V}, V_{DD} = -24\text{ V},$ $I_D = -10\text{ A}, R_G = 3.3\Omega$		10		ns
Rise Time	$t_r$			19.2		
Turn-Off Delay Time	$t_{d(OFF)}$			53.6		
Fall Time	$t_f$			14.4		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = -1\text{ A}$		-0.7	-1.2	V

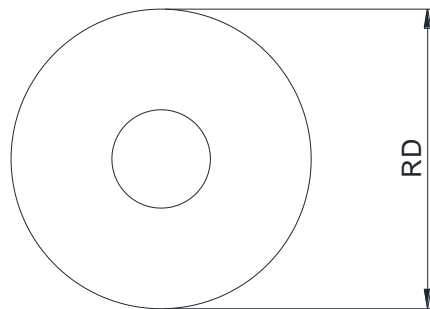
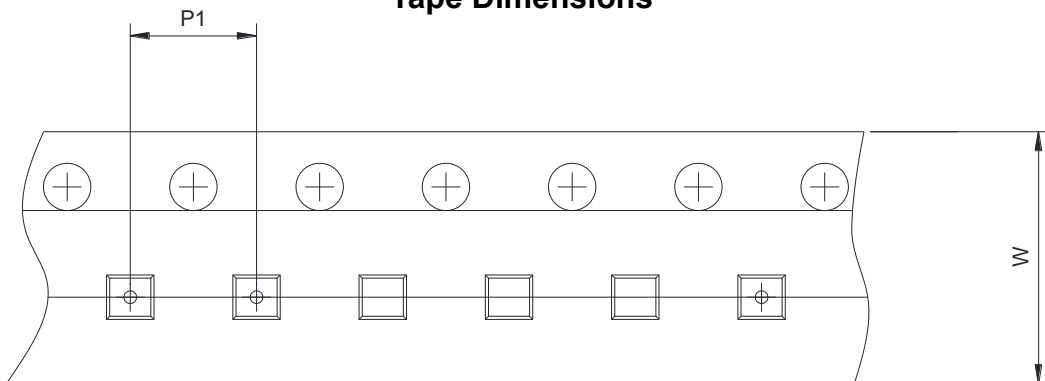
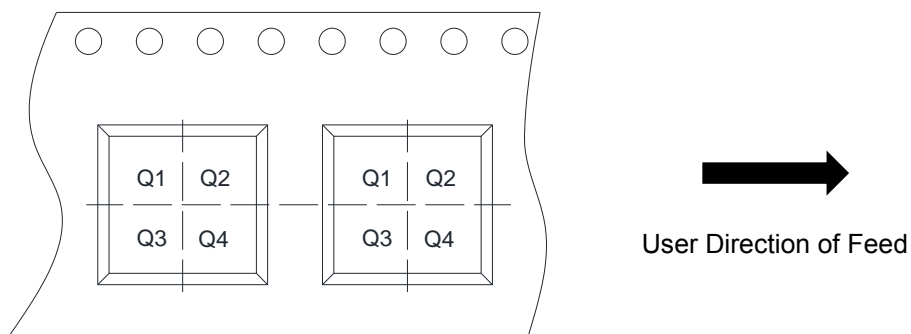
**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output Characteristics <sup>e</sup>**

**Transfer Characteristics <sup>e</sup>**

**On-Resistance vs. Drain Current <sup>e</sup>**

**On-Resistance vs. Gate-to-Source Voltage <sup>e</sup>**

**On-Resistance vs. Junction Temperature <sup>e</sup>**

**Threshold voltage vs. Temperature**


**Capacitance**

**Body Diode Forward Voltage<sup>e</sup>**

**Single pulse power**

**Safe operating power**

**Gate Charge Characteristics**


**Transient thermal response (Junction-to-Case)**

**Transient Thermal Response (Junction-to-Ambient)**

**PACKAGE OUTLINE DIMENSIONS**
**PDFN3333-8L**

**TOP VIEW**

**BOTTOM VIEW**

**SIDE VIEW**

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.80	0.90
b	0.25	0.30	0.35
c	0.14	0.15	0.20
D	3.10	3.30	3.50
D1	3.05	3.15	3.25
D2	2.35	2.45	2.55
e	0.55	0.65	0.75
E	3.10	3.30	3.50
E1	2.90	3.00	3.10
E2	1.64	1.74	1.84
H	0.32	0.42	0.52
K	0.59	0.69	0.79
L	0.25	0.40	0.55
L1	0.10	0.15	0.20
L2	-	-	0.15
$\theta$	8°	10°	12°

**TAPE AND REEL INFORMATION**
**Reel Dimensions**

**Tape Dimensions**

**Quadrant Assignments For PIN1 Orientation In Tape**


RD	Reel Dimension	<input type="checkbox"/> 7inch	<input checked="" type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input type="checkbox"/> 8mm	<input checked="" type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm	<input type="checkbox"/> 4mm <input checked="" type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input checked="" type="checkbox"/> Q1	<input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4



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